

[illegible]

/ Descriptions

F G G H I J K L M N O

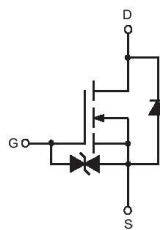
/ Features

P Q % R - S T U V W X Y Z % [\ V W O] V ^ _ ` O < = B C O

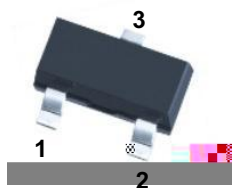
/ Applications

a b c d % e f X g h R - O

/ Equivalent Circuit



/ Pinning



i

i

i

/ Marking

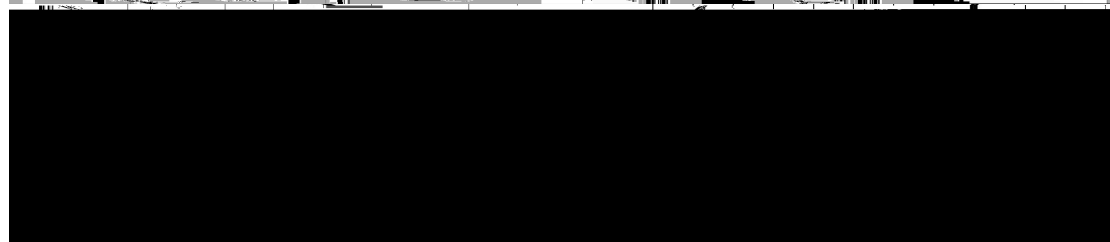
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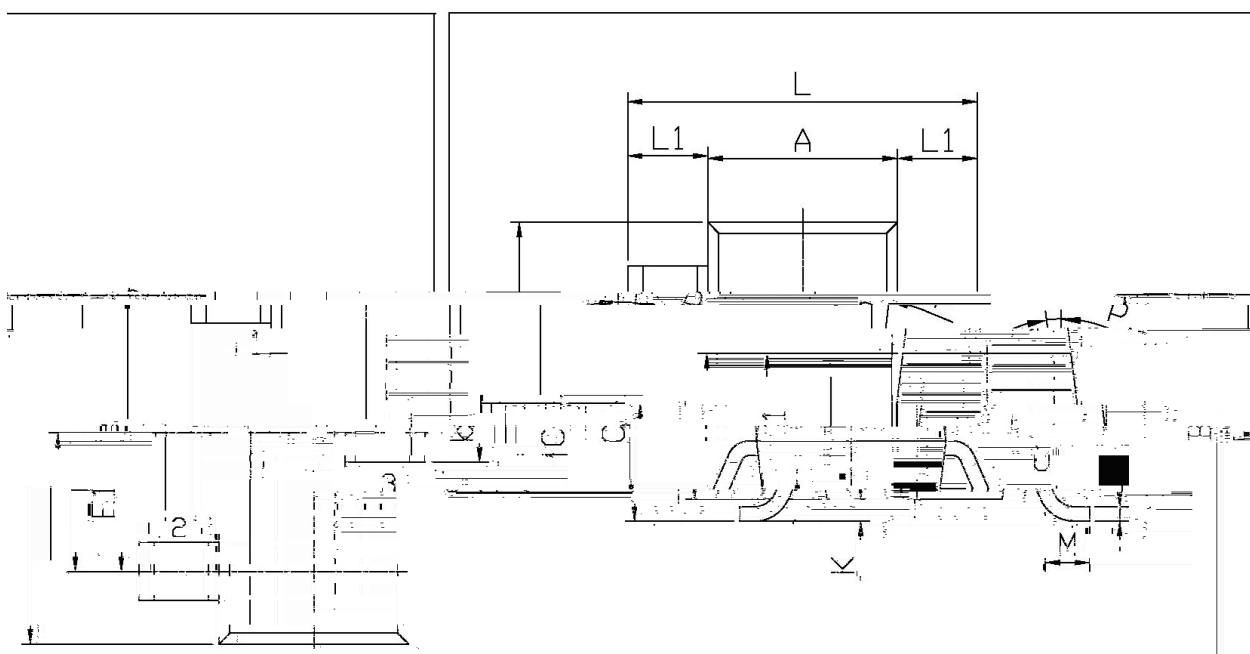
/ Absolute Maximum Ratings(Ta=25)

j k	l m	k n	o h
		~	℃

/ Electrical Characteristics(Ta=25)

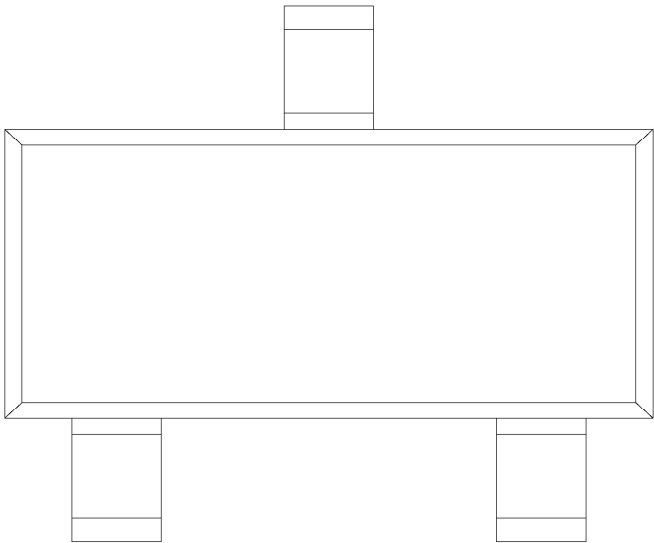
j k	l m	p q r s	t u n	v w n	t x n	o h





Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
		0.45			0.90
		1.75			0.05
		2.70			0.10
		0.85			0.05
		0.35			0.55

/ Marking Instructions



y z i
i { | } ~ '
i { w m ~ '



() / Temperature Profile for IR Reflow Soldering(Pb-Free)

说明：

- 、预热温度 ~ °C , 时间 ~ °C
- 、峰值温度 ± °C , 时间持续为 ± °C ±
- 、焊接制程冷却速度为 ~ °C °C

/ Resistance to Soldering Heat Test Conditions

温度： ± °C 时间： ± °C